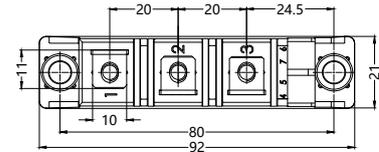
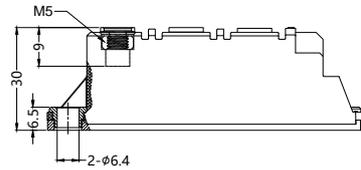
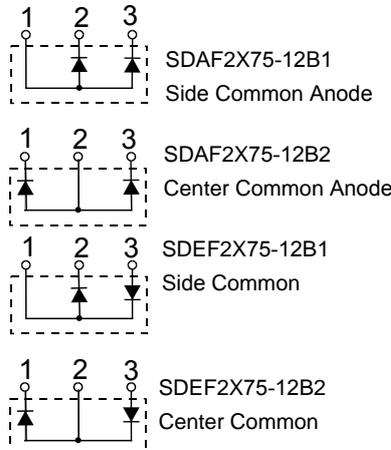
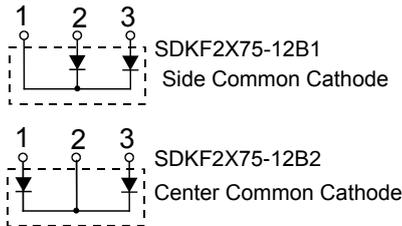


# SDKF2x75-12B SDEF2x75-12B SDAF2x75-12B

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules



Dimensions in mm (1mm=0.0394")



	VRSM V	VRRM V
SDKF2x75-12B1	1200	1200
SDKF2x75-12B2	1200	1200

	VRSM V	VRRM V
SDAF2x75-12B1	1200	1200
SDAF2x75-12B2	1200	1200

	VRSM V	VRRM V
SDEF2x75-12B1	1200	1200
SDEF2x75-12B2	1200	1200

Symbol	Test Conditions	Maximum Ratings	Unit
IFRMS	T <sub>C</sub> =75°C	107	A
IFAVM	T <sub>C</sub> =75°C; rectangular, d=0.5	2 x 75	
IFRM	t <sub>p</sub> <10us; rep. rating, pulse width limited by T <sub>VJM</sub>	TBD	
IFSM	T <sub>VJ</sub> =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	A
	T <sub>VJ</sub> =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	
I <sup>2</sup> t	T <sub>VJ</sub> =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	A <sup>2</sup> s
	T <sub>VJ</sub> =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	
T <sub>VJ</sub> T <sub>stg</sub> T <sub>Hmax</sub>		-40...+150 -40...+125 110	°C
P <sub>tot</sub>	T <sub>case</sub> =25°C	280	W
V <sub>ISOL</sub>	50/60Hz, RMS t=1min I <sub>ISOL</sub> ≤1mA t=1s	3000 3600	V~
M <sub>d</sub>	Mounting torque (M5) Terminal connection torque (M5)	2.50-4/22-35 2.50-4/22-35	Nm/lb.in.
ds	Creeping distance on surface	12.7	mm
dA	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s <sup>2</sup>
Weight		108	g



# SDKF2x75-12B G8 9 : &I +) !%&6 G8 5 : &I +) !%&6

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

Symbol	Test Conditions	Characteristic Values		Unit
		typ.	max.	
I <sub>R</sub>	T <sub>VJ</sub> =25°C; V <sub>R</sub> =V <sub>RRM</sub>		2	mA
	T <sub>VJ</sub> =25°C; V <sub>R</sub> =0.8·V <sub>RRM</sub>		0.5	
	T <sub>VJ</sub> =125°C; V <sub>R</sub> =0.8·V <sub>RRM</sub>		34	
V <sub>F</sub>	I <sub>F</sub> =75A; T <sub>VJ</sub> =125°C		1.85	V
	T <sub>VJ</sub> =25°C		2.17	
	I <sub>F</sub> =225A; T <sub>VJ</sub> =125°C		2.58	
	T <sub>VJ</sub> =25°C		2.64	
V <sub>TO</sub>	For power-loss calculations only		1.48	V
r <sub>T</sub>			3.65	m
R <sub>thJH</sub> R <sub>thJC</sub>	DC current DC current		0.550 0.450	K/W
t <sub>rr</sub> I <sub>RM</sub>	I <sub>F</sub> =150A; T <sub>VJ</sub> =100°C V <sub>R</sub> =600V; T <sub>VJ</sub> =25°C -di/dt=200A/us; T <sub>VJ</sub> =100°C	250	300 22 33	ns A A

### FEATURES

- \* International standard package
- \* Copperbase plate
- \* Glass passivated chips
- \* Short recovery time
- \* Low switching losses
- \* Soft recovery behaviour
- \* UL File NO.E310749
- \* RoHS compliant

### APPLICATIONS

- \* Antiparallel diode for high frequency switching devices
- \* Free wheeling diode in converters and motor control circuits
- \* Inductive heating and melting
- \* Uninterruptible power supplies (UPS)
- \* Ultrasonic cleaners and welders

### ADVANTAGES

- \* High reliability circuit operation
- \* Low voltage peaks for reduced protection circuits
- \* Low noise switching
- \* Low losses



**Sirectifier®**

# SDKF2x75-12B G8 9: &I +) !%&6 G8 5: &I +) !%&6

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

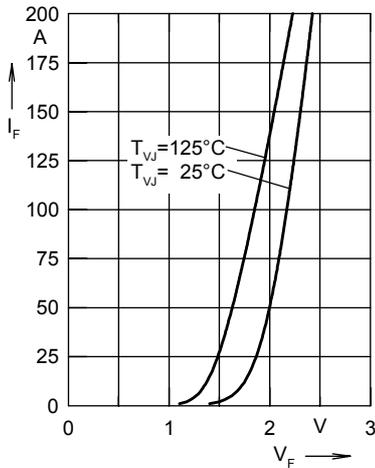


Fig. 1 Forward current  $I_F$  versus voltage drop  $V_F$  per leg

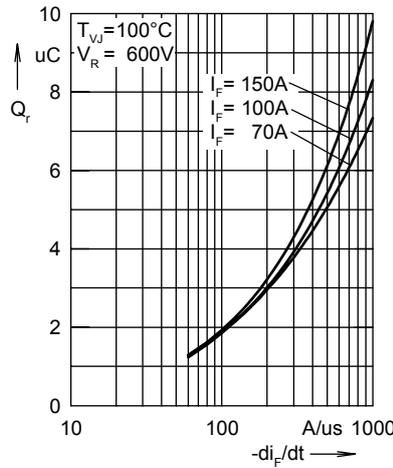


Fig. 2 Reverse recovery charge  $Q_r$  versus  $-di_F/dt$

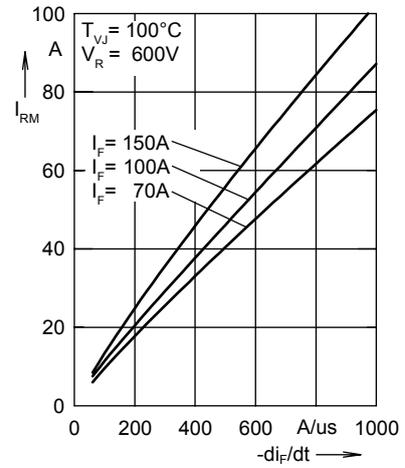


Fig. 3 Peak reverse current  $I_{RM}$  versus  $-di_F/dt$

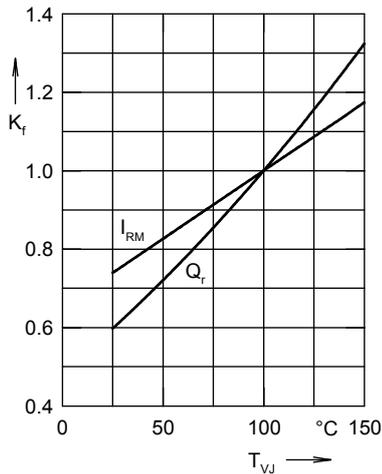


Fig. 4 Dynamic parameters  $Q_r$ ,  $I_{RM}$  versus junction temperature  $T_{VJ}$

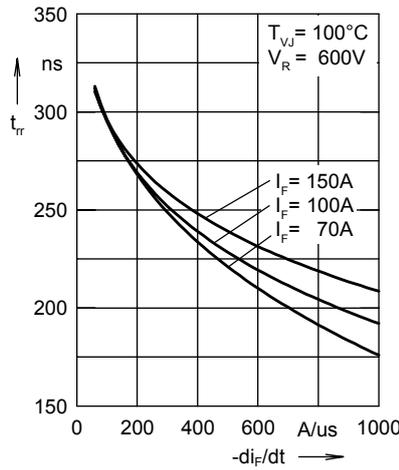


Fig. 5 Recovery time  $t_{tr}$  versus  $-di_F/dt$

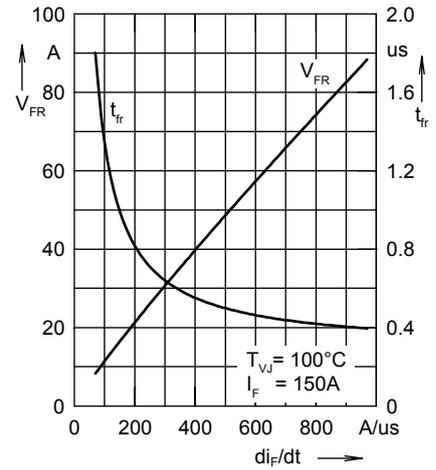


Fig. 6 Peak forward voltage  $V_{FR}$  and  $t_{tr}$  versus  $di_F/dt$

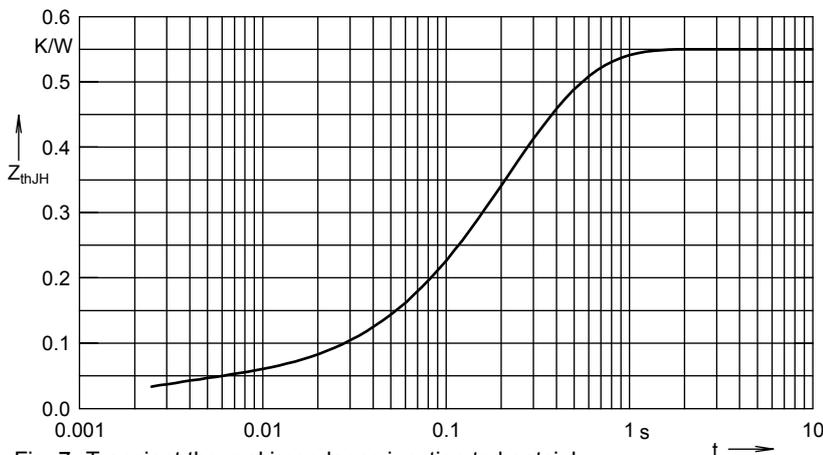


Fig. 7 Transient thermal impedance junction to heatsink

Constants for  $Z_{thJH}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.037	0.002
2	0.138	0.134
3	0.093	0.25
4	0.282	0.274